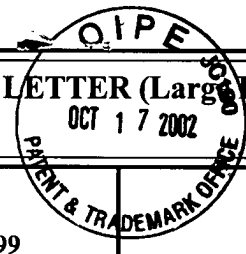


28158



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|--|---------------------------------------|-------------------------------|------------------------------------|
| AMENDMENT TRANSMITTAL LETTER (Large Entity) | | | Docket No. JEL 30763 PCT |
| Applicant(s): Masanori MINAMIO, et al. | | | |
| Serial No. 09/380,312 | Filing Date August 31, 1999 | Examiner L. C. Cruz | Group Art Unit 2815 |

Invention:
RESIN MOLDED TYPE SEMICONDUCTOR DEVICE AND A METHOD OF MANUFACTURING THE SAME

TO THE ASSISTANT COMMISSIONER FOR PATENTS:

Transmitted herewith is an amendment in the above-identified application.
 The fee has been calculated and is transmitted as shown below.

| CLAIMS AS AMENDED | | | | | | |
|--|-------------------------------------|-----------------------------|--------------------------------|---------|-------------------|-----------------|
| | CLAIMS REMAINING AFTER AMENDMENT | HIGHEST # PREV. PAID FOR | NUMBER EXTRA CLAIMS PRESENT | RATE | ADDITIONAL FEE | |
| TOTAL CLAIMS | 30 - | 20 = | 10 x | \$18.00 | \$180.00 | |
| INDEP. CLAIMS | 9 - | 9 = | 0 x | \$84.00 | \$0.00 | |
| Multiple Dependent Claims (check if applicable) <input type="checkbox"/> | | | | | | \$0.00 |
| TOTAL ADDITIONAL FEE FOR THIS AMENDMENT | | | | | | \$180.00 |

- ☐ No additional fee is required for amendment.
- ☐ Please charge Deposit Account No. _____ in the amount of _____
A duplicate copy of this sheet is enclosed.
- ☒ A check in the amount of **\$180.00** to cover the filing fee is enclosed.
- ☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. **19-4375**
A duplicate copy of this sheet is enclosed.
 - ☒ Any additional filing fees required under 37 C.F.R. 1.16.
 - ☒ Any patent application processing fees under 37 CFR 1.17.

Signature

Dated: **October 17, 2002**

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| |
|---|
| I certify that this document and fee is being deposited on _____ with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231. |
| <i>Signature of Person Mailing Correspondence</i> |
| <i>Typed or Printed Name of Person Mailing Correspondence</i> |

CC:



#19/C

1-17-03

L. Spruell

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

fee OK

Inventors: Masanori Minamio, et al.

Art Unit: 2815

Appln. No.: 09/380,312 /

Examiner: L.C. Cruz

Filed: August 31, 1999 /

For: RESIN MOLDED TYPE SEMICONDUCTOR DEVICE AND A
METHOD OF MANUFACTURING THE SAMEAMENDMENTAssistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action mailed July 17, 2002, the Applicants hereby request amendment of the above-identified application as follows:

IN THE DRAWINGS

Proposed revisions of Figs. 1, 3, 5 and 6 are submitted herewith for approval, with a Letter to the Official Draftsman.

IN THE CLAIMS

Please amend the claims to read as follows (Exhibit I contains a marked up version):

1. (Amended) A resin molded type semiconductor device comprising: a semiconductor chip which is mounted on a die pad of a lead frame; thin metal wires which electrically connect terminals of an upper face of said semiconductor chip to inner lead portions

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